

SOT1931-1(SC)

plastic thermal enhanced quad flat package; no leads; 24 terminals; 0.5 mm pitch, 4 mm x 4 mm x 1.98 mm body

18 July 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HQFN24
Package style descriptive code	HQFN (thermal enhanced quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	12-07-2019
Manufacturer package code	98ASA01095D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	4	-	mm
package width	-	4	-	mm
package height	-	1.98	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	24	-	



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2 Package outline

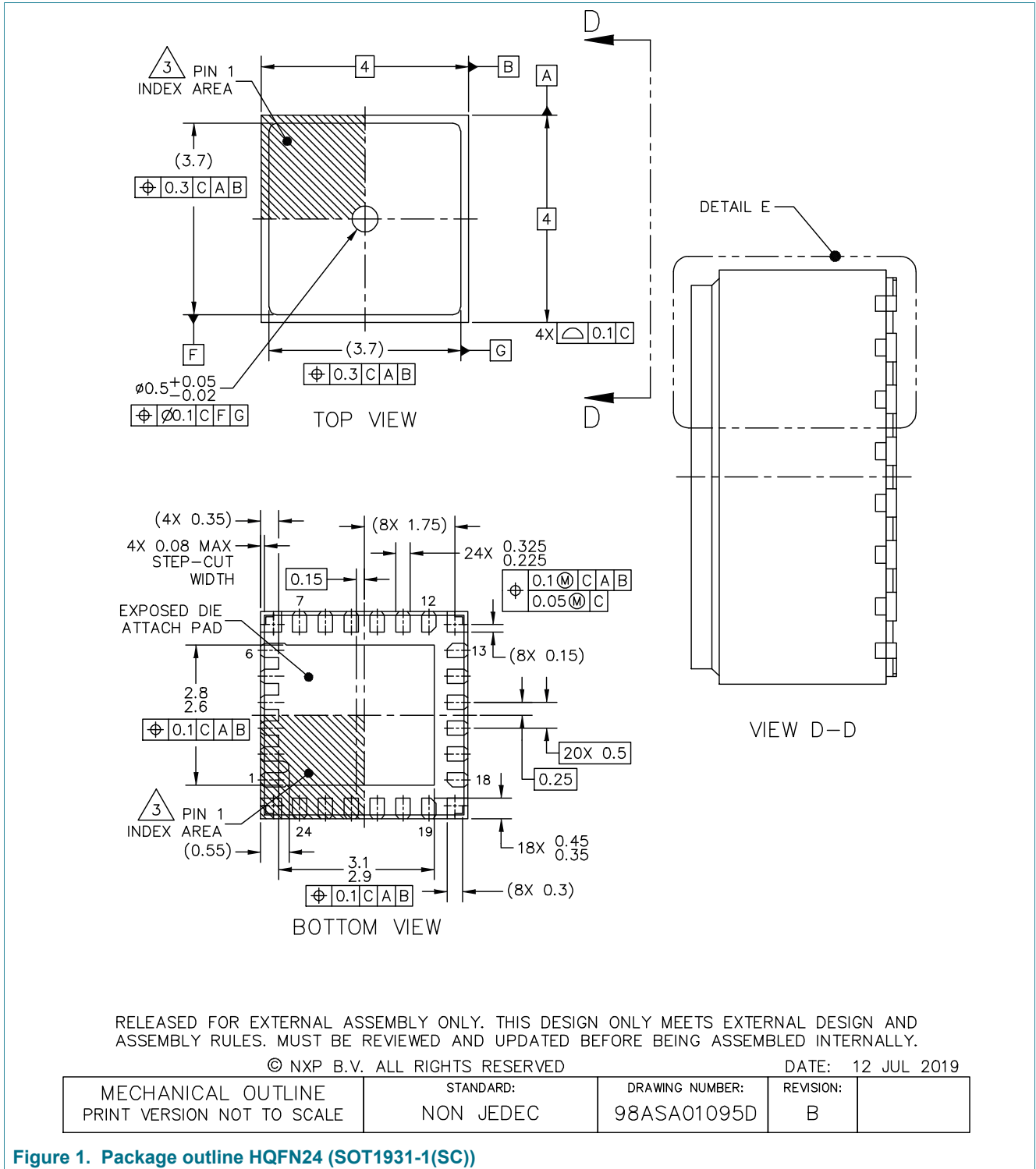
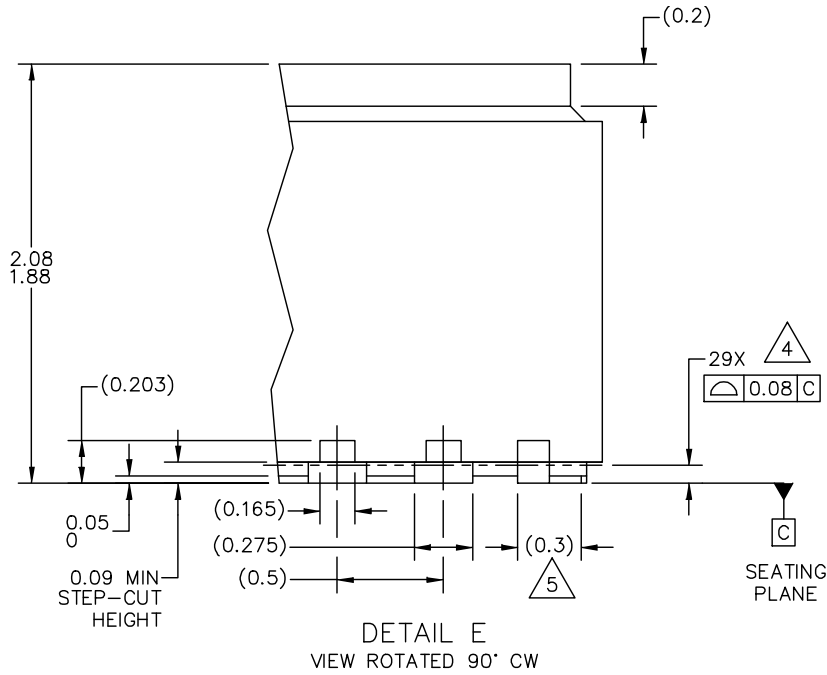


Figure 1. Package outline HQFN24 (SOT1931-1(SC))

plastic thermal enhanced quad flat package; no leads; 24 terminals; 0.5 mm pitch, 4 mm x 4 mm x 1.98 mm body



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DATE: 12 JUL 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01095D	REVISION: B	
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Figure 2. Package outline detail of HQFN24 (SOT1931-1(SC))

3 Soldering

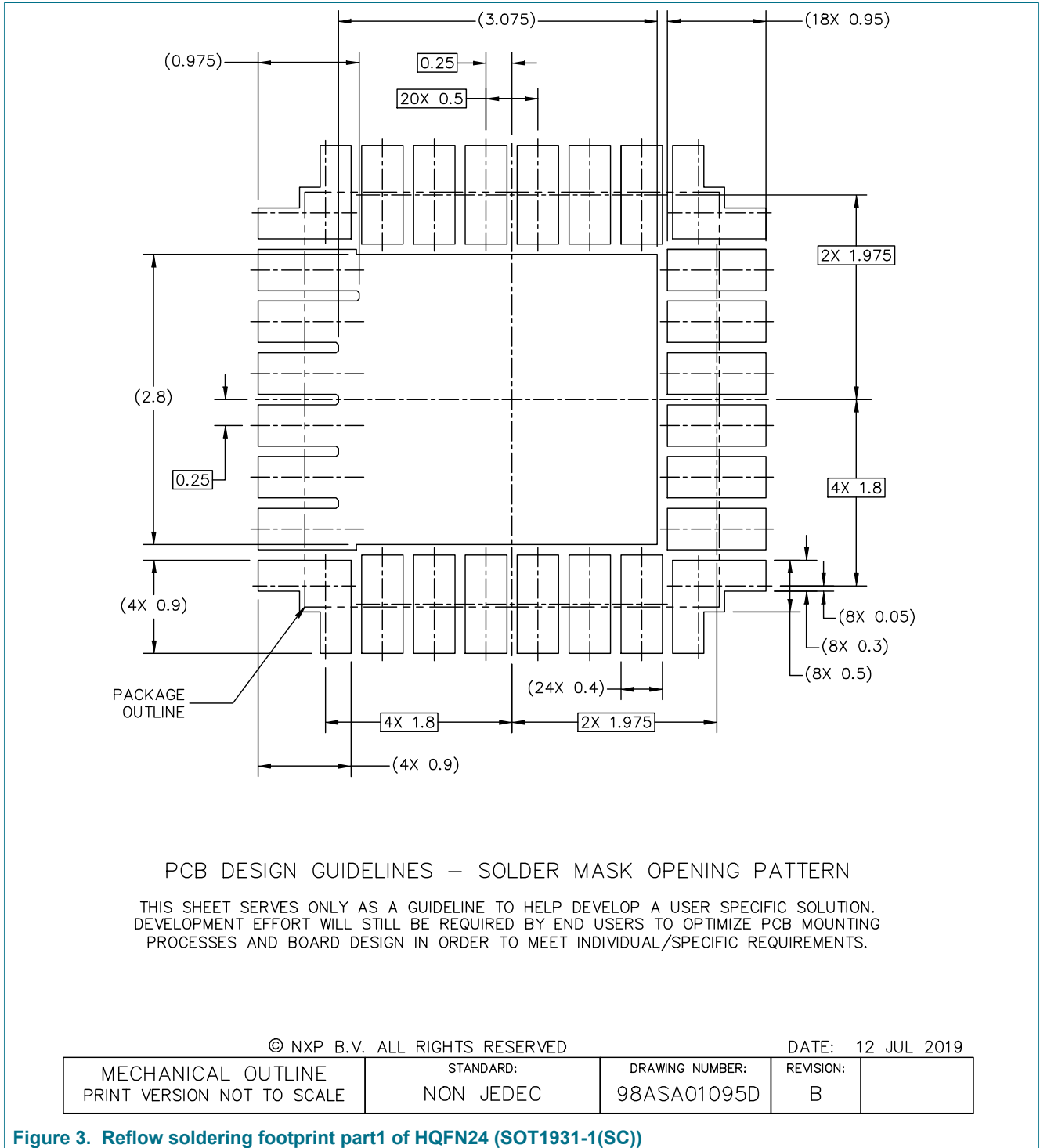
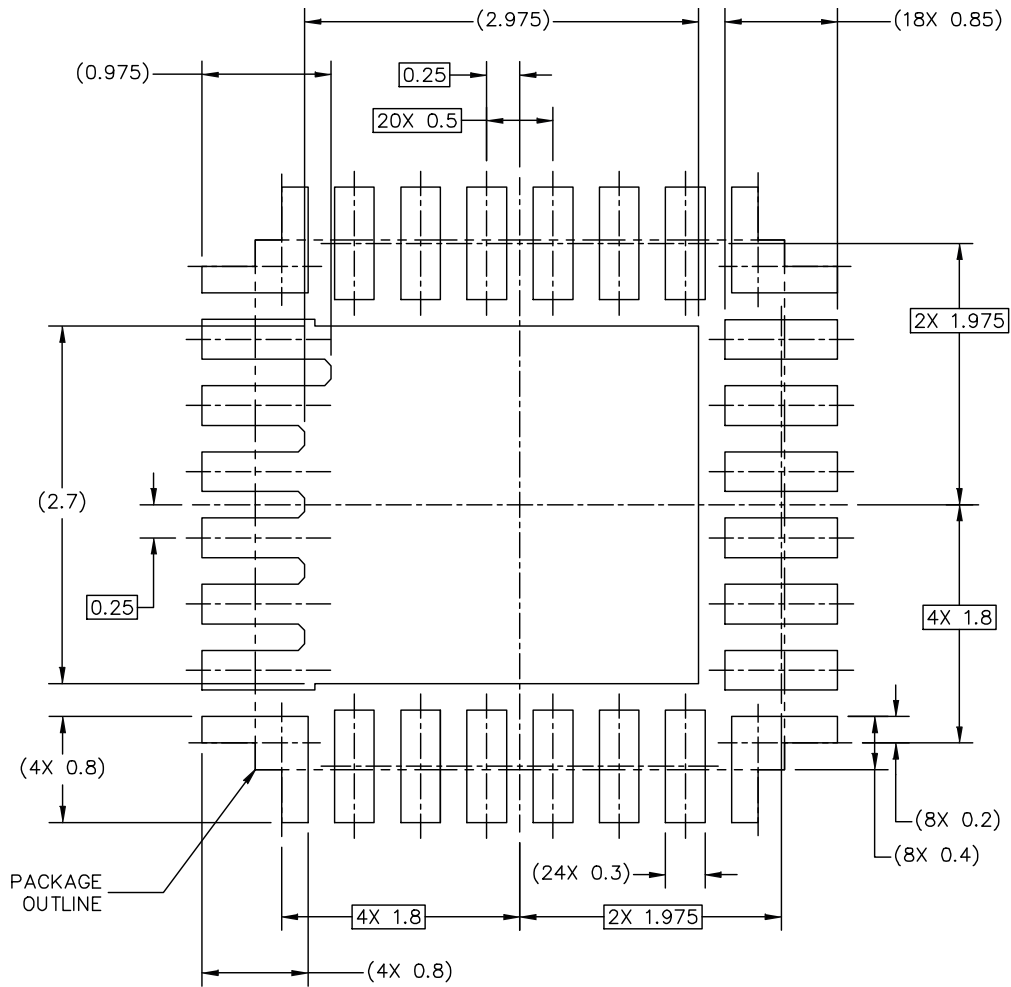


Figure 3. Reflow soldering footprint part1 of HQFN24 (SOT1931-1(SC))

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PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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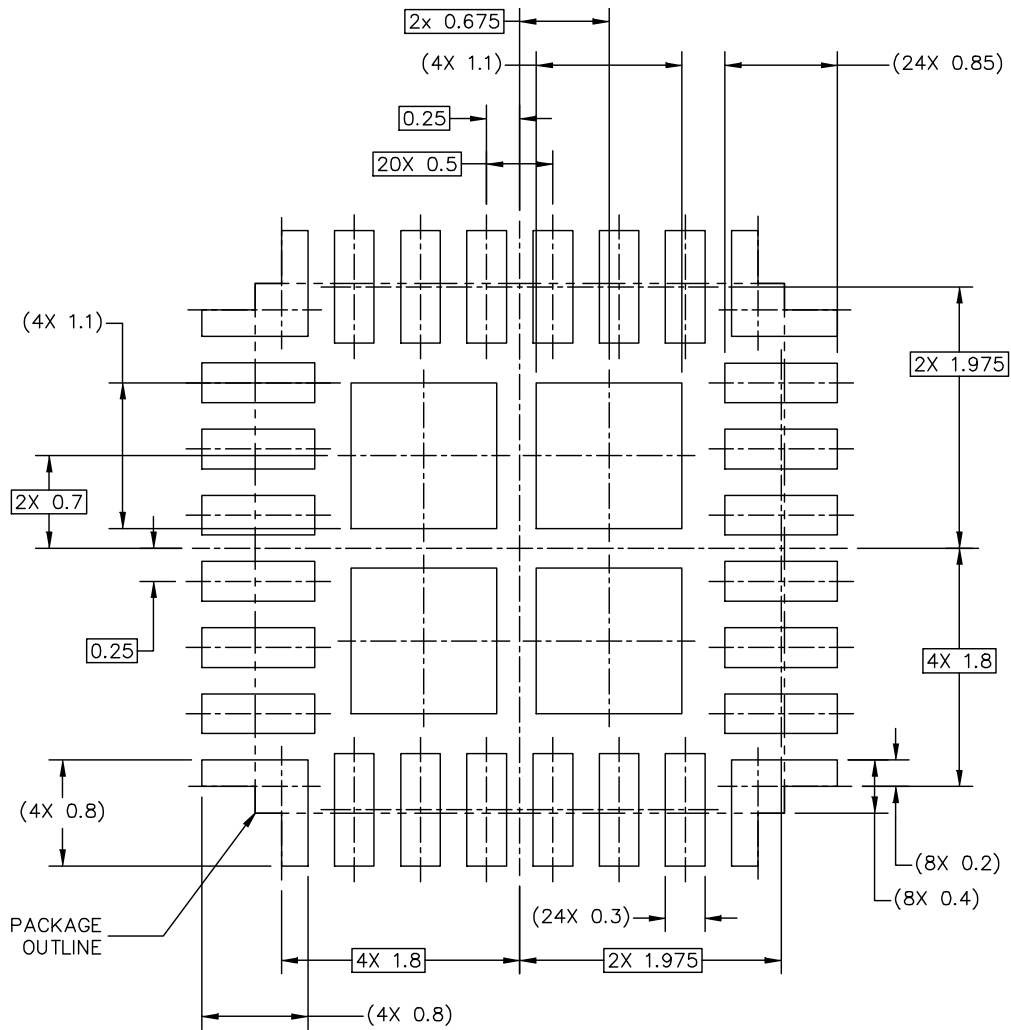
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Figure 4. Reflow soldering footprint part2 of HQFN24 (SOT1931-1(SC))

plastic thermal enhanced quad flat package; no leads; 24 terminals; 0.5 mm pitch, 4 mm x 4 mm x 1.98 mm body



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 of HQFN24 (SOT1931-1(SC))

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
5. ANCHORING PADS.

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Figure 6. Package outline note HQFN24 (SOT1931-1(SC))

4 Legal information

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